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THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. 09/148,723  
Priority Filing Date September 3, 1998  
Inventor Warren M. Farnworth et al.  
Assignee Micron Technology, Inc.  
Priority Group Art Unit 3729  
Priority Examiner D. Tugbang  
Attorney's Docket No. MI22-981  
Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate

RESPONSE TO MAY 22, 2000 OFFICE ACTION

PRELIMINARY AMENDMENT TO ACCOMPANY CPA FILING

Suppl

To: BOX CPA  
Assistant Commissioner for Patents  
Washington, D.C. 20231

From: Frederick M. Fliegel, Ph.D. (Tel. 509-624-4276; Fax 509-838-3424)  
Wells, St. John, Roberts, Gregory & Matkin P.S.  
601 W. First Avenue, Suite 1300  
Spokane, WA 99201-3817

Sir:

Responsive to the Final Office Action dated May 22, 2000,  
Applicant amends and remarks as follows [unless otherwise indicated,  
deletions are bracketed, additions are underlined]:

AMENDMENTS

In the Claims